

SUN NETRA CP3200 ADVANCED REAR TRANSITION MODULES

KEY FEATURES

INDUSTRY-STANDARD, LEADING PERFORMANCE

- Enable NEPS to simplify system integration and leverage the ATCA standard and reusability across multiple ATCA blade server solutions
- Enhance I/O connectivity density and increase system thermal reliability
- Industry-standard connectors and pin assignments ensure ease of use, reuse, and design flexibility
- Optimized system-level cooling and filtering per slot for ATCA I/O
- Intelligent Platform Management Interface (IPMI) management entities controlled by a Module Management Controller (MMC)
- Maximum real estate and panel space for I/O connector breakout
- Industry-standard connector and lane mapping specified with 10 Gigabit Ethernet, SAS, and more
- NEBS Level 3 compliant and hot swappable, ensuring optimal durability and suitability for telecommunications applications

Oracle's Sun Netra CP3200 Advanced Rear Transition Modules (AdvancedRTMs) are ATCA and NEBS Level 3-compliant carrier-grade expansion cards that can be attached to the Sun Netra CP3220, Sun Netra CP3250, Sun Netra CP3260 and Sun Netra CP3270 ATCA blade servers to provide simplified rear access connectivity to a variety of I/O devices such as hard drives, Fibre Channel connections, and 10 GbE networks.



Sun Netra CP3200 AdvancedRTMs leverage the ATCA standard and promote reusability across multiple ATCA blade server solutions.

A Common Rear I/O Architecture for ATCA

By leveraging the ATCA standard, Sun Netra CP3200 AdvancedRTMs enable Network Equipment Providers (NEPs) to facilitate system integration of multiple applications in a single shelf, enhance I/O connectivity density, and increase system thermal reliability. They also promote reusability across multiple ATCA blade server solutions, as well as the ability to replace the blade servers without disconnecting the cables, providing for simplified management. This enables Oracle and Oracle independent hardware vendor (IHV) partners to create market-leading solutions for Sun Netra ATCA 10 GbE blades.

Highest Level of Interoperability and I/O Density Available Today

Sun Netra CP3200 AdvancedRTMs offer you the highest level of interoperability and I/O density available today. They also provide for Advanced Mezzanine Card (AMC)-specified system management, Tyco Z-PACK HM-Zd connector, AMC-defined hot-swapping, and port/lane mapping. In addition, they conform to PICMG 3.0 ATCA card specification for RTM cards.

The CPU and AMC combination can be a system-level integration challenge, depending on the placement of components. Many system designers require

additional I/O for add-on devices, such as hard drives as well as Fibre Channel and 10 GbE connections. The architecture of Sun Netra CP3200 AdvancedRTMs provides for these additional options while enabling dedicated cooling for optimized system-level efficiency. Deploying I/O interfaces on the rear of the system facilitates extremely reliable, tested cooling configurations on a per-slot basis.

Sun Netra CP3200 Advanced Rear Transition Modules Specifications

Sun Netra CP3200 AdvancedRTMs are a series of three RTMs:

- Sun Netra CP3200 ARTM-HD
- Sun Netra CP3200 ARTM-FC
- Sun Netra CP3200 ARTM-10 GbE

Each is designed to support a specific usage model with leading-edge innovation and efficiency.

- Direct-attached storage (DAS), dual SAS hard disk drives, SAN connectivity
- Dual Fibre Channel or high-speed networking
- Dual/quad 10 GbE

All three are built to the same world-class Oracle standards for proven performance; all support Sun Netra CP3220, Sun Netra CP3250, Sun Netra CP3260 and Sun Netra CP3270 ATCA blade servers; and all provide enhanced flexibility by running Oracle's Solaris 10, Linux, and Windows operating systems.

Product Specifications

ARTM-HD
<ul style="list-style-type: none"> • Current blade servers supported: Sun Netra CP3220, Sun Netra CP3250, Sun Netra CP3260 and Sun Netra CP3270 ATCA blade servers • Disks: Up to two 2.5 in. SAS HDDs (300 GB, bootable, RAID 0) • Disk controller: LSI 1068E PCI Express (PCIe) to eight-port SAS controller chip • Secondary I/O: Up to two egress SAS ports (3 GB/sec, bootable, dual host) • Qualified with the NEBS Level 3-certified Sun StorageTek 2530 array
ARTM-FC
<ul style="list-style-type: none"> • Host bus adapter: 4 Gb/sec HB dual-port (Emulex technology), multipath I/O support • Ethernet interfaces: Six 1 GbE interfaces, two with small form factor-pluggable (SFP) support • Expansion port: PCIe x4 • Qualified with NEBS Level 3-certified Sun StorageTek 2540 and Sun StorageTek 6140 arrays
ARTM-10 GbE
<ul style="list-style-type: none"> • Ports: Two 10 GbE SFP+ ports, hardware TCAM and classification, multiple DMA engines; two multithreaded 1 GbE SFP ports, hardware TCAM and classification, multiple DMA engines • Optional: Two multithreaded 10 GbE ports, Oracle's UltraSPARC T2 processor-based network interface unit (NIU)—PICMG 3.1 programmable bypass

Common Architecture
<ul style="list-style-type: none"> • Maximum power: 25 W, powered through the Sun Netra ATCA node board • Networking interfaces: 1 GbE from host ATCA blades • Serial craft ports: One • System management: MMC
Dimensions
<ul style="list-style-type: none"> • Single-slot • Height: 233.35 mm (9.19 in.) 8RU • Depth: 70 mm (2.76 in.) • Width: 30 mm (1.18 in.)
Regulations and Standards
<ul style="list-style-type: none"> • Conforms to AdvancedRTM interface specification • NEBS Level 3 compliant • Tyco Z-PACK HM-Zd connector • AMC-defined hot-swapping and port/lane mapping • Conforms to PICMG 3.0 ATCA card specification for RTM cards • Complies with IEEE 1101.11 mechanical standards and PICMG 2.10 specifications

Warranty

Visit oracle.com/sun/warranty for Oracle's global warranty support information on Sun products.

Services

Visit oracle.com/sun/services for information on Oracle's service program offerings for Sun products.

Contact Us

For more information about Oracle's Sun Netra CP3200 Advanced Rear Transition Modules, please visit oracle.com/sun or call +1.800.786.0404 to speak to an Oracle representative.



Oracle is committed to developing practices and products that help protect the environment

Copyright © 2008, 2009, Oracle and/or its affiliates. All rights reserved.

This document is provided for information purposes only and the contents hereof are subject to change without notice. This document is not warranted to be error-free, nor subject to any other warranties or conditions, whether expressed orally or implied in law, including implied warranties and conditions of merchantability or fitness for a particular purpose. We specifically disclaim any liability with respect to this document and no contractual obligations are formed either directly or indirectly by this document. This document may not be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, without our prior written permission.

Oracle and Java are registered trademarks of Oracle and/or its affiliates. Other names may be trademarks of their respective owners.

AMD, Opteron, the AMD logo, and the AMD Opteron logo are trademarks or registered trademarks of Advanced Micro Devices. Intel and Intel Xeon are trademarks or registered trademarks of Intel Corporation. All SPARC trademarks are used under license and are trademarks or registered trademarks of SPARC International, Inc. UNIX is a registered trademark licensed through X/Open Company, Ltd. 0809